

IN THE CLAIMS

Claims 1-35 (cancelled).

Claim 36 (new). A method of manufacturing an electronic device in which a plasma treatment is carried out on a device substrate which is mounted on a support electrode facing a perforated gas feeding electrode, a reactive plasma being generated in a space between the electrodes from a mixture of reaction gases which is fed into the space through at least the perforated electrode, wherein a primary mixture of gases flows in a direction across the substrate from a first area of the space to which it is supplied by a first supply line fitted with a mass flow controller, and a second supply line fitted with a mass flow controller feeds a secondary mixture of gases to a second area of the space through the perforated electrode, the second area being excluded from the first area, the primary mixture of gases comprising a first reaction gas which is depleted at a different rate as the plasma treatment than a second reaction gas in the primary mixture which is richer in the first reaction gas than the primary mixture supplied by the first supply line, whereby the plasma treatment is carried out more uniformly over the area of the supporting electrode.